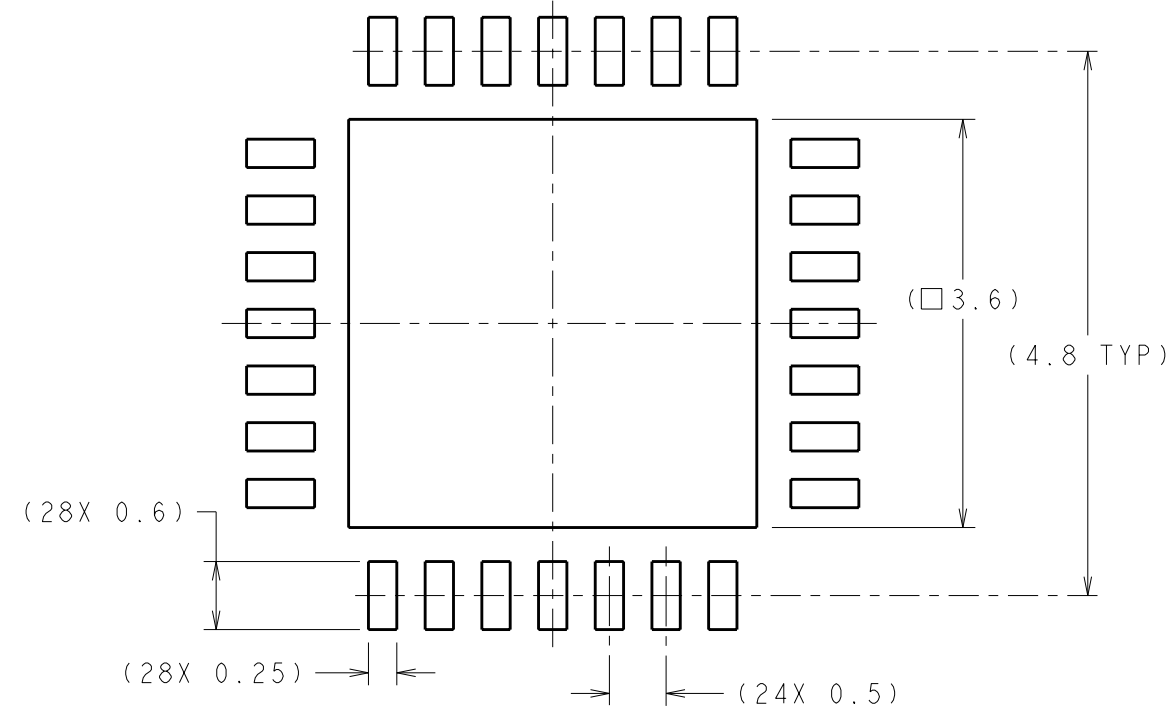
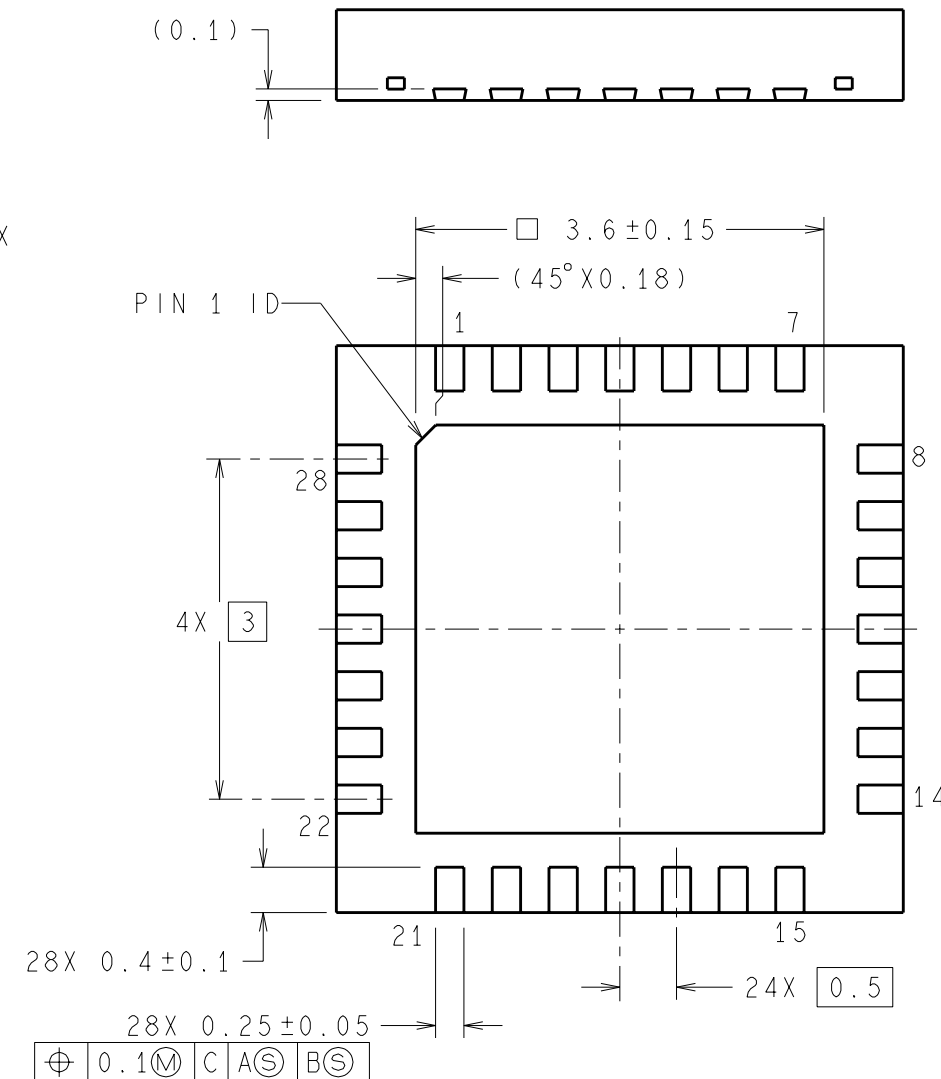
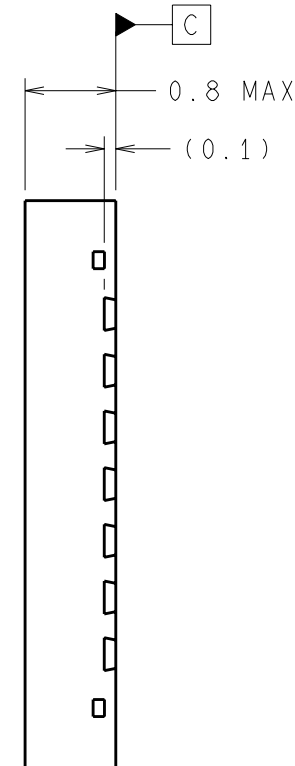
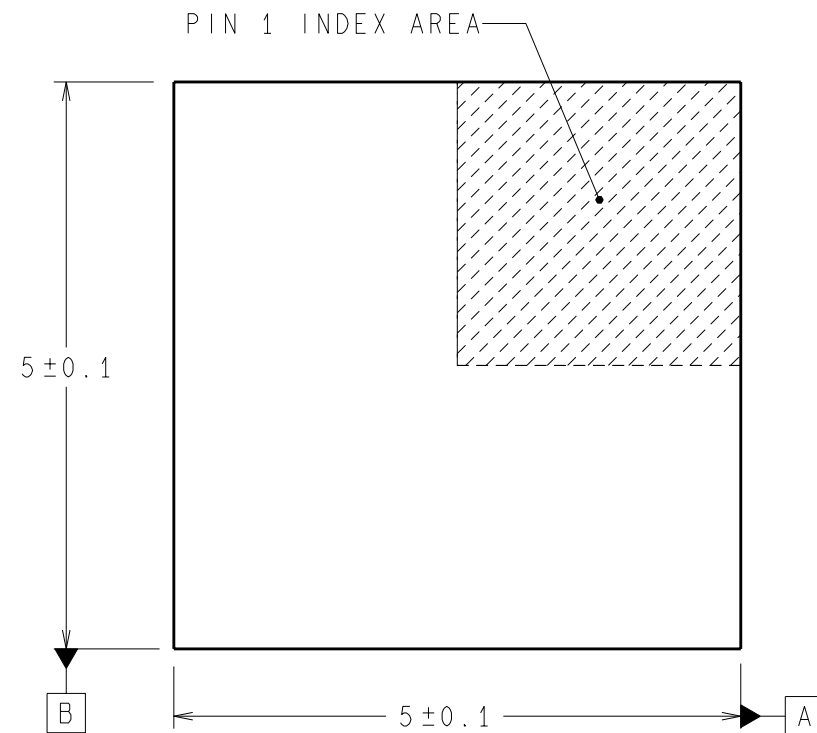


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	1044	05/28/2003	HR/MS/SN
B	DIMENSION 3.6±0.15 WAS 3.6±0.1; DIMENSION 28X 0.4±0.1 WAS 28X 0.4±0.05	1110	08/26/2003	AS/TL/SN



**DIMENSIONS ARE IN MILLIMETERS**  
DIMENSIONS IN ( ) FOR REFERENCE ONLY

**RECOMMENDED LAND PATTERN**



NOTES: UNLESS OTHERWISE SPECIFIED.

- FOR SOLDER THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE ([www.national.com](http://www.national.com)).
- MAXIMUM ALLOWABLE METAL BURR ON LEAD TIPS AT THE PACKAGE EDGES IS 76 MICRONS.
- REFERENCE JEDEC REGISTRATION MO-220, VARIATION WHHD-3.

APPROVALS		DATE	 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	HAFIZA RAMLEY	05/28/2003		
DFTG. CHK.	THANH LEQUANG	08/26/2003	<b>LLP, PLASTIC, QUAD,</b> <b>5x5x0.8mm BODY, 28 LD</b> <b>0.5mm PITCH, NO PULLBACK</b>	
ENGR. CHK.	N. SANTHIRAN	08/26/2003		
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
 MM	NTS	B	(SC)MKT-SQA28A	B
FORMERLY: N/A			SHEET 1 of 1	